

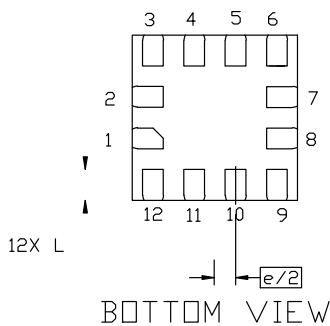
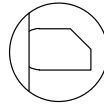
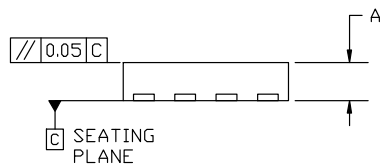
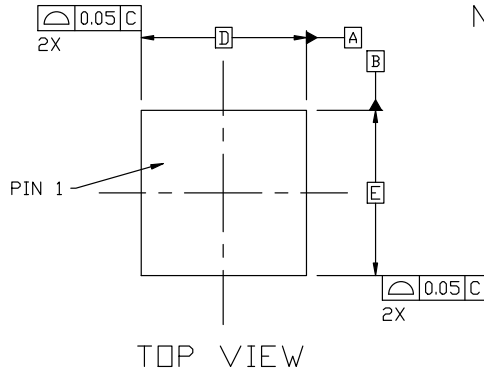


**X2QFN12 1.60x1.60x0.37, 0.40P**  
CASE 722AD  
ISSUE A

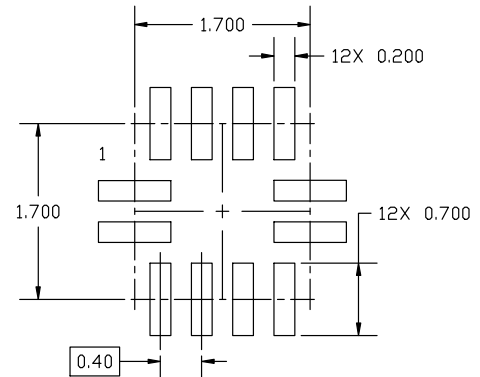
DATE 15 NOV 2023

NOTES:

1. DIMENSIONS AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.34	0.37	0.40
b	0.15	0.20	0.25
D	1.60 BSC		
E	1.60 BSC		
e	0.40 BSC		
L	0.25	0.30	0.35
L1	0.10 (REF)		
M	45° (REF)		



**RECOMMENDED MOUNTING FOOTPRINT**

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCES MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>X2QFN12 1.60x1.60x0.37, 0.40P</b>	<b>PAGE 1 OF 1</b>

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